



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET

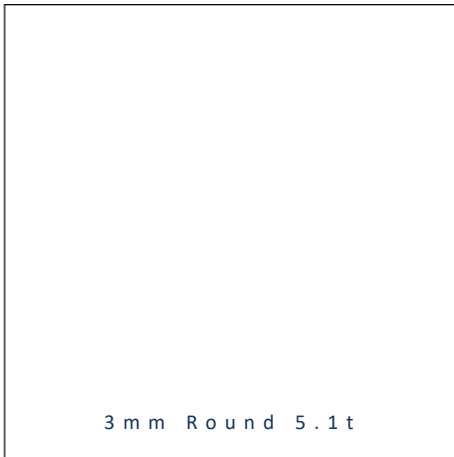


- ▶ PTH/THT Lamp
- ▶ 3mm Round 5.1t
- ▶ Ultraviolet (400nm)

N0Q58L93 (Bulk)
N0Q58L93T (Taping)



Release Date: 06 April 2021 Version: A1.0



3mm Round 5.1t

RoHS
Compliant



FEATURES:

- **Package:** 3mm Round 5.1t PTH/THT Lamp
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 3.1V
- **Luminous Intensity (typ.):** 45mcd@20mA
- **Colour:** Ultraviolet
- **Wavelength:** 400nm
- **Viewing angle:** 80°
- **Materials:**
 - Die: InGaN
 - Resin: Epoxy (Purple Diffused)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+85°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - Dominant Wavelength
- **Soldering methods:** Hand; Soldering Heat (DIP)
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 500pcs/Bulk; 2000pcs/Taping

APPLICATIONS:

- Curing Device
- Nail Curing

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I_F	30	mA
Peak Forward Current Duty 1/10@1KHz	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Reverse Current @5V	I_R	10	μ A
Operating Temperature	T_{OPR}	-40~+85	°C
Storage Temperature	T_{STG}	-40~+85	°C

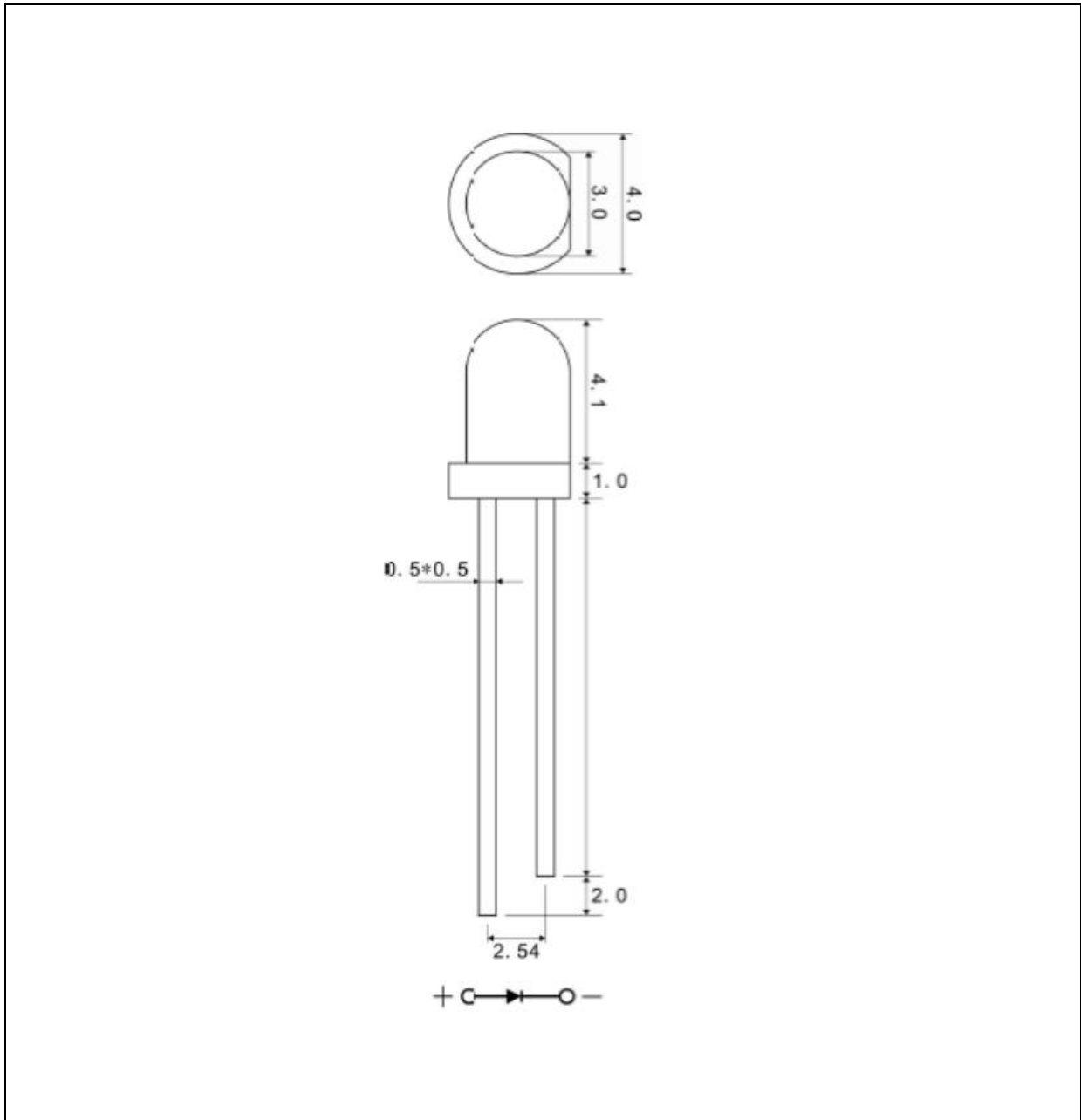
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	2.8	---	3.4	V	$I_F=20mA$
Luminous Intensity	I_e	10	---	80	mcd	$I_F=20mA$
Dominant Wavelength	λ_D	390	---	410	nm	$I_F=20mA$
Spectral Line Half Bandwidth	$\Delta \lambda$	---	18	---	nm	$I_F=20mA$
Viewing Angle	$2\theta_{1/2}$	---	80	---	deg	$I_F=20mA$

1. Luminous Intensity (I_v) $\pm 10\%$, Forward Voltage (V_F) $\pm 0.1V$, Dominant Wavelength (λ_D) $\pm 1nm$

OUTLINE DIMENSION:

Package Dimension:



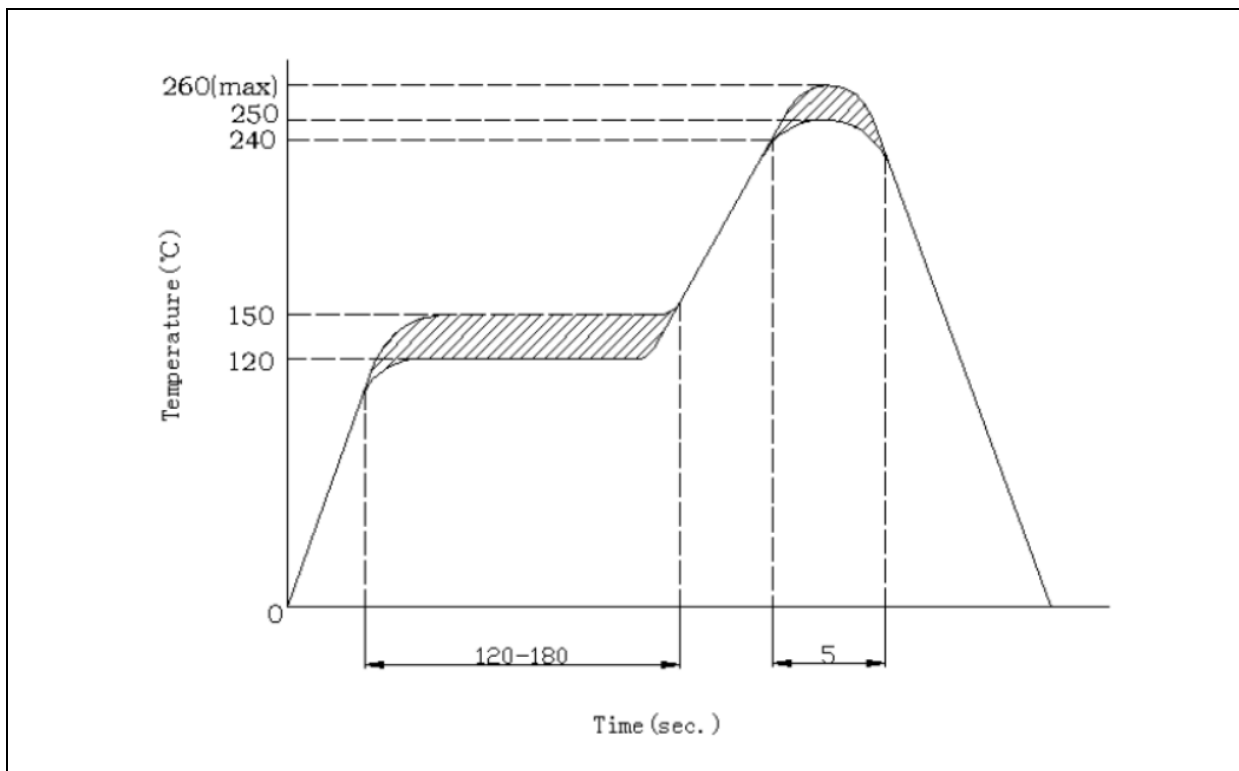
1. All dimensions are in millimetre (mm).
2. Tolerance ± 0.3 mm, unless otherwise noted.

RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 260°C Max.
- Soldering Time: 3 seconds \pm 1 sec.
- Maxima reflow soldering: 1 time.

Soldering Heat (DIP):

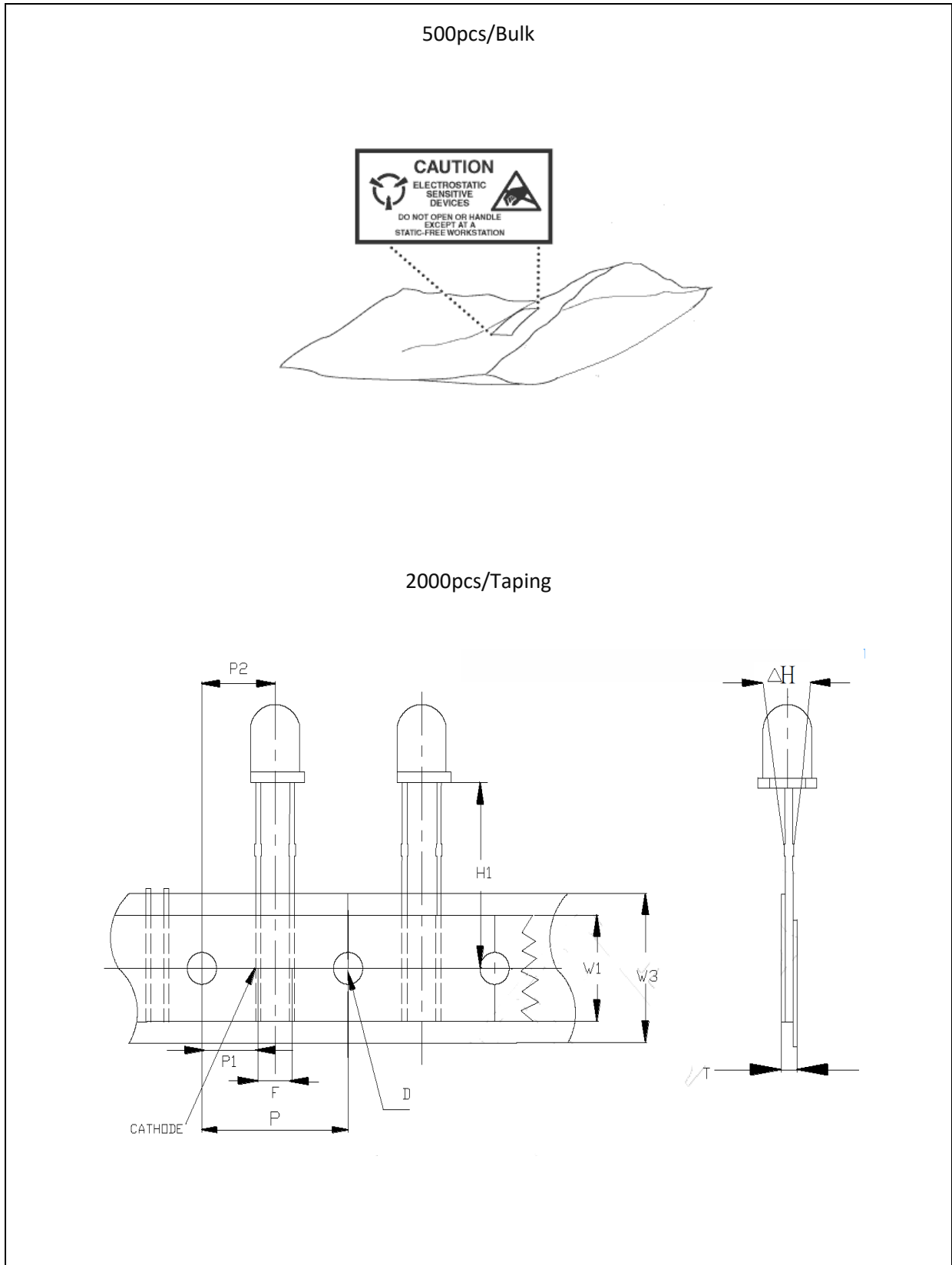


Note:

1. Maxima reflow soldering: 1 time.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

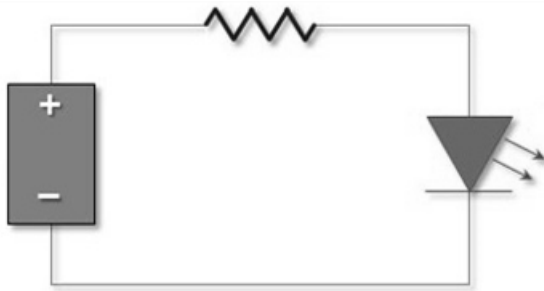
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	06/04/2021	Datasheet set-up.